Am27S29/Am27S29A/Am27S29SA



4,096-Bit (512x8) Bipolar PROM

DISTINCTIVE CHARACTERISTICS

- High Speed
- Highly reliable, ultra-fast programming Platinum-Silicide fuses
- High programming yield

- · Low-current PNP inputs
- · High-current open-collector and three-state outputs
- Fast chip select

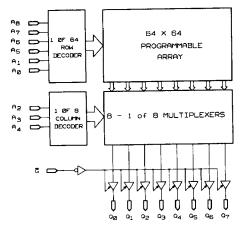
GENERAL DESCRIPTION

The Am27S29 (512-words by 8-bits) is a Schottky TTL Programmable Read-Only Memory (PROM).

This device has three-state outputs, compatible with low-power Schottky bus standards capable of satisfying the

requirements of a variety of microprogrammable controls, mapping functions, code conversion, or logic replacement. Easy word depth expansion is facilitated by an active LOW (\$\overline{G}\$) output enable.

FUNCTIONAL BLOCK DIAGRAM



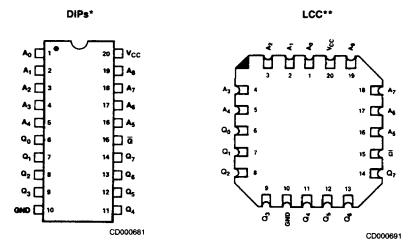
BD006182

PRODUCT SELECTOR GUIDE

Three-State Part Number	Am27	S29SA	Am27	'S29A	Am27S29			
Address Access Time	30 ns	40 ns	35 ns	45 ns	55 ns	70 ns		
Operating Range	С	М	С	М	С	М		

CONNECTION DIAGRAMS

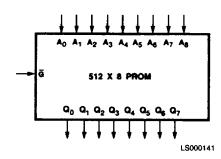
Top View



- *Also available in a 20-pin Flatpack. Pinout identical to DIPs.
- **Also available in a 20-pin PLCC. Pinout identical to LCC.

Note: Pin 1 is marked for orientation.

LOGIC SYMBOL

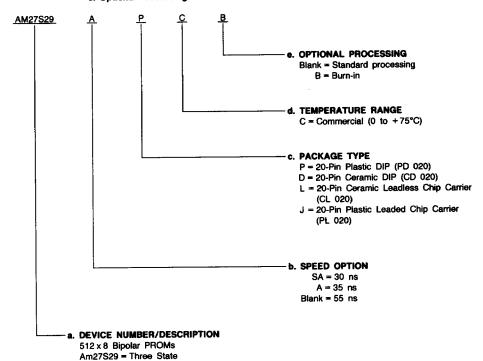


ORDERING INFORMATION

Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid Combinations								
AM27S29								
AM27S29A	PC, PCB, DC, DCB,							
AM27S29SA								

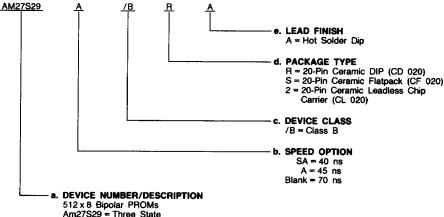
Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

ORDERING INFORMATION **APL Products**

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. CPL (Controlled Products List) products are processed in accordance with MIL-STD-883C, but are inherently non-compliant because of package, solderability, or surface treatment exceptions to those specifications. The order number (Valid Combination) for APL products is formed by a combination of:

- a. Device Number b. Speed Option (if applicable)
- c. Device Class
- d. Package Type e. Lead Finish



Valid Combinations								
AM27S29								
AM27S29A	/BRA, /BSA, /B2A							
AM27S29SA								

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations or to check for newly released valid combinations.

Group A Tests

Group A Tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11,

MILITARY BURN-IN

Military burn-in is in accordance with the current revision of MIL-STD-883, Test Method 1015, Conditions A through E. Test conditions are selected at AMD's option.

PIN DESCRIPTION

An - As Address (inputs)

The 9-bit field presented at the address inputs selects one of 512 memory locations to be read from.

Q₀ – Q₇ **Data Output Port**

The outputs whose state represents the data read from the selected memory locations.

Output Enable (Input)

Provides direct control of the Q-output buffers. Outputs disabled forces all three-state outputs to a floating or highimpedance state.

Enable = G

Disable = G

V_{CC} Device Power Supply Pin

The most positive of the logic power supply pins.

Device Power Supply Pin

The most negative of the logic power supply pins.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature 65 to +150°C Ambient Temperature with
Power Applied 55 to +125°C
Supply Voltage 0.5 V to +7.0 V
DC Voltage Applied to Outputs
(Except During Programming) 0.5 V to + VCC Max.
DC Voltage Applied to Outputs
During Programming21 V
Output Current into Outputs During
Programming (Max. Duration of 1 sec) 250 mA
DC Input Voltage0.5 V to +5.5 V
DC Input Current30 mA to +5 mA

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices Ambient Temperature (T _A)	+ 75°C 5.25 V
Military (M) Devices* Case Temperature (T _C)	-125°C ⊦5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

*Military product 100% tested at T_C = +25°C, +125°C, and -55°C.

DC CHARACTERISTICS over operating ranges unless otherwise specified (for APL Products, Group A, Subgroups 1, 2, 3 are tested unless otherwise noted)

Parameter Symbol	Parameter Description		Test Condition	Min.	Тур.	Max.	Unit	
V _{OH} (Note 1)	Output HIGH Voltage	V _{CC} = Min., I _{OH} V _{IN} = V _{IH} or V _{II}			2.4			v
VOL	Output LOW Voltage	V _{CC} = Min., l _{OL} V _{IN} = V _{IH} or V _I					0.50	٧
VIH	Input HIGH Level	Guaranteed inpo			2.0			V
VIL	Input LOW Level	Guaranteed inpo					0.8	٧
T _{IL}	Input LOW Current	V _{CC} = Max., V _{II}	ı = 0.45 V				-0.250	mA
ЯН	Input HIGH Current	V _{CC} = Max., V _{II}	₁ = 2.7 V			l	25	μΑ
ISC (Note 1)	Output Short-Circuit Current	V _{CC} = Max., V _C	UT = 0.0 V (No	te 3)	-20		-90	mA
lcc	Power Supply Current	All inputs = GNI V _{CC} = Max.	0				160	mA
Vi	Input Clamp Voltage	V _{CC} = Min., I _{IN}	≖ - 18 mA				-1.2	
	Output Leakage Current	V _{CC} = Max.	(Note 1)	V _O = V _{CC}			40	μA
ICEX		VG = 2.4 V			-40			
C _{IN}	Input Capacitance	V _{IN} = 2.0 V @ T _A = 25°C	f = 1 MHz (Note	e 4) V _{CC} = 5 V;		4		ρF
Cout	Output Capacitance	V _{OUT} = 2.0 V (T _A = 25°C	@ f = 1 MHz (N	ote 4)V _{CC} = 5 V;		8		

1. This applies to three-state devices only. Notes:

- 2. VIL and VIH are input conditions of output tests and are not themselves directly tested. VIL and VIH are absolute voltages with respect to device ground and include all overshoots due to system and/or tester noise. Do not attempt to test these values without suitable equipment.
- 3. Not more than one output should be shorted at a time. Duration of the short circuit should not be more than one second.
- 4. These parameters are not 100% tested, but are periodically evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (for APL Products, Group A, Subgroups 9, 10, 11 are tested unless otherwise noted*)

			"SA" Version			"A" Version			Standard Version						
			COM'L		MIL		COM.F		MIL		COM'L		MIL		
No.	Parameter Symbol	Parameter Description	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Units
1	TAVQV	Address Valid to Output Valid Access Time		30		40		35		45		55		70	ns .
2	TGVQZ	Delay from Output Enable Valid to Output Hi-Z		20		25		20		25		25		30	ns
3	TGVQV	Delay from Output Enable Valid to Output Valid		20		25		20		25		25		30	ns

See also Switching Test Circuits.

Notes: 1. Tests are performed with input transition time of 5 ns or less, timing reference levels of 1.5 V, and input pulse levels of 0 to 3.0 V using test load in Figure A.

2. TGVQZ is measured at steady state HIGH output voltage -0.5 V and steady state LOW output voltage +0.5 V ouput levels using

the test load in Figure B.

*Subgroups 7 and 8 apply to functional tests.

SWITCHING TEST CIRCUITS



A. Output Load for all A-C tests except TGVQZ

B. Output Load for TGVQZ

- Notes: 1. All device test loads should be located within 2" of device output pin.
 - S₁ is open for Output Data HIGH to Hi-Z and Hi-Z to Output Data HIGH tests.
 S₁ is closed for all other AC tests.

 - 3. Load capacitance includes all stray and fixture capacitance.

SWITCHING WAVEFORMS KEY TO SWITCHING WAVEFORMS

